Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (previously presented) Lustrous copper-based metal flakes that contain, in addition to copper, at least one additional metallic alloy component and are produced via vacuum deposition of metal films onto a carrier sheet, stripping of the films from the carrier sheet, and subsequent comminuting of the films.

2. (original) Lustrous copper-based metal flakes according to claim 1, characterized in that the flakes contain at least 51% copper and between 1 and 49% aluminum.

3. (currently amended) Lustrous copper-based metal flakes according to claim 1~~ or 2~~, characterized in that the flakes contain silicon as an additional alloy component.

4. (currently amended) Lustrous copper-based metal flakes according to ~~any of~~ claim~~s~~ 1~~ through 3~~, characterized

in that the flake-shaped effect pigment has plane-parallel surfaces and a thickness between 10 and 100 nm, preferably between 20 and 60 nm.

5. (currently amended) Lustrous, copper-based metal flakes according to ~~any of~~ claim~~s~~ 1 ~~through 4~~, characterized in that the surface of the pigment particles is coated with an anticorrosive layer.

6. (original) Lustrous copper-based metal flakes according to claim 5, characterized in that the anticorrosive layer contains aluminum oxide, silicon oxide, phosphate, phosphoric acid, phosphoric ester, phosphinic acid, silanes, organically modified silicates, titanates, zirconates or methacrylate-based polymer layers or combinations of these compounds.

7. (currently amended) A method for producing lustrous, copper-based metal flakes according to ~~any of~~ claim~~s~~ 1 ~~through 6~~ with the following process steps:

a) optionally applying a release coat on a carrier sheet;

b) applying of a metal film onto the release coat or the carrier sheet;

c) stripping of the metal film; and

d) comminuting to pigment particles.

8. (original) A method according to claim 7, characterized in that applying of the metal film takes place through evaporation of the alloy components.

9. (original) A method according to claim 7, characterized in that applying of the metal film takes place through separate evaporation of the alloy components.

10. (original) A method according to claim 7, characterized in that applying of the metal film takes place through separate evaporation of an alloy and one or more additional components.

11. (currently amended) A method according to ~~any of~~ claim~~s~~ 7~~ through 10~~, characterized in that applying of the metal film takes place through electron beam, resistance heating, or radiation heating.

12. (currently amended) A method according to ~~any of~~ claim~~s~~ 7~~ through 11~~, characterized in that applying of the metal film takes places through flash evaporation, simultaneous evaporation, or jumping beam evaporation.